

811-64

A Two Component Potting Compound

Description:

The **811-64** System is a two component, high performance, room temperature curing, highly filled potting / encapsulating compound. **811-64** is the carbon filled version of **812-48**.

Advantages:

The **811-64** System is a mixed system that features a low viscosity for good flow properties and moderate set up time. **811-64** is primarily used for potting or ruggedizing heat sensitive electronic parts. The low viscosity mixture exhibits exceptional wetting and void free pouring during application. **811-64** is a lower shrinkage version of the **810-70**.

Physical Properties:

	<u>Resin</u>	<u>Hardener</u>
	811-64A	811-64B
Color:	Black	Clear
Specific Gravity:	1.62	1.02
Lb/gal:	13.50	8.50
Mix Ratio (By Weight):	100	12

Shelf Life: (Sealed containers)

One Year @ 25°C (both A+B). Hand agitation of the Resin component is recommended after long standing to insure best results.

Instructions:

Combine the Resin and the Hardener in the ratio listed above. Mix by hand or mechanical mixer until material is uniform in appearance.

Cure Schedules:

Overnight or 16 hours @ 25°C will yield 80% of the systems full potential.

% Full Cure:	80%	100%
Cure Temperature:	25°C (77°F)	25°C (77°F)
Cure Time (hours):	16	96 (4 days)

Pot Life (100 grams) @ 25°C (77°F) = 45 minutes

Cured Properties:

Shore Hardness, measured @ 25°C: 85D
Operating Temperature Range, (°C): -20°C to +100°C

Storage and Handling:

Normal storage and handling is at room temperature. Use standard mixing and housekeeping procedures to minimize the risk of spills and contact with the surrounding materials.

All values reported above are typical values, and are reported as a means of reference. Individual testing should be done to determine actual results, tested at specific conditions.